



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: OH ET AL. DOCKET NO.: WK2K1070
SERIAL NO: 10/015,374 EXAMINER: WILLIAMS
FILED: 12/12/2001 ART UNIT: 2826
TITLE: STACKING STRUCTURE OF SEMICONDUCTOR CHIPS AND
SEMICONDUCTOR PACKAGE USING IT

HOK
Andy
Juncin
6/6/03

Commissioner for Patents Weiss, Moy & Harris, P.C.
P.O. Box 1450 4204 N. Brown Avenue
Alexandria, VA 22313-1450 Scottsdale, AZ 85251-3989

May 15, 2003

I hereby certify that on the 15th day of May, 2003, this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, 22313-1450.


Jeffrey D. Moy

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MAY 29 2003
TECHNOLOGY CENTER 2800

AMENDMENT

Dear Sir:

This is in response to the Office Action dated January 15, 2003 in regards to the above identified patent application. Please amend the subject patent application as follows: